

Agency Contact:
Kenn Durrence
The Hoffman Agency
(408) 975-3097
kdurrence@hoffman.com

Company Contact:
Chris Stai
Advanced Interconnect Technologies
(408) 331-7325
cstai@aitemail.com

**ADVANCED INTERCONNECT TECHNOLOGIES ANNOUNCES
THAT AMI SEMICONDUCTOR IS NOW IN VOLUME PRODUCTION
WITH STACKED DIE QFN PACKAGE**

AIT's QFN Solution To Be Used in High-volume Consumer Applications

SINGAPORE, January 29, 2007 – Advanced Interconnect Technologies (AIT) today announced that AMI Semiconductor (AMIS) is in full production mode with AIT's stacked die quad flat package no leads (QFN) module for various consumer electronics applications. AIT's stacked die QFN package gives AMIS an ideal solution for deployment, as it provides overall power savings due to better electrical connectivity, a small footprint for increased board savings, and a lower overall total cost of ownership.

“We chose AIT's stacked die QFN package, as it was ideal for the way that we will be deploying these modules in high-volume consumer electronics applications,” said Aran Idan, general manager, Netlist Conversion SDP at AMI Semiconductor. “Today's consumer applications need a small footprint, better thermal management and an increase in power savings, which we have found in AIT's stacked die QFN package.”

AIT's stacked die QFN-MCM (multi-chip module) package features system in package (SiP) technology that is designed to place two or more die in a single package, resulting in smaller packages and thus reducing costs. The SiP framework is designed to provide higher levels of integration, which decreases the number of needed components and trims the size and routing complexity of the printed circuit board. This stacking technology in a low-cost QFN package makes it an ideal solution for space-conscious designers of various consumer devices, such as AMIS.

“The stacked die QFN package is part of AIT’s commitment in providing the market with world-class technology solutions that exceed customer expectations, while preserving a low total cost of ownership,” said Bruno Guilmart, chief executive officer at AIT. “The stacked die QFN package was specifically designed to address the needs of next-generation designers such as AMIS, who need the latest and greatest packaging technology to realize volume deployment for new and compelling consumer applications.”

About Advanced Interconnect Technologies (AIT)

Advanced Interconnect Technologies is a global provider of semiconductor assembly and test services for many of the world’s most successful electronics companies. The company’s turnkey services include design, assembly, test, failure analysis, and electrical and thermal characterization. AIT has received recognition for its field service and product yields from several of the industry’s leading semiconductor device manufacturers. The company is also ISO 9001:2000, ISO 14001 and ISO/TS16949-2002 certified. With approximately 4,000 employees worldwide, AIT has factory locations in Batam, Indonesia and Sunnyvale, Calif. For more information about the company, its products and services please visit its Web site at www.aithome.com.

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